

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yoshihito YOSHIKAWA	07/01/2009
Motoki OHTA	07/01/2009
RECEIVING PARTY DATA	
Name:	HITACHI METALS, LTD.
Street Address:	2-1, Shibaura 1-chome
City:	Minato-ku, Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12529148
CORRESPONDENCE DATA	
Fax Number:	(202)293-7860
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202-293-7060
Email:	bmurray@SUGHRUE.COM
Correspondent Name:	SUGHRUE MION, PLLC
Address Line 1:	2100 Pennsylvania Avenue, NW
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20037-3213
ATTORNEY DOCKET NUMBER:	Q114717
NAME OF SUBMITTER:	Peter D. Olexy
Total Attachments: 1 source=ASSIGNMENT_AS_FILED#page1.tif	

CH \$40.00 12529148

500949936

PATENT
REEL: 023169 FRAME: 0211

ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar(\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI METALS, LTD., a corporation organized under the laws of Japan, located at 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI METALS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MAGNETIC ALLOY, AMORPHOUS ALLOY RIBBON, AND MAGNETIC PART

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith,

and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI METALS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI METALS, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

Date Signed

(発明者フルネームサイン)

(署名日)

1)	<u>Yoshihito Yoshizawa</u> Yoshihito YOSHIKAWA	<u>July 1, 2009</u>
2)	<u>Motoki Ohta</u> Motoki OHTA	<u>July 1, 2009</u>
3)	_____	_____
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____

PATENT